

IN THE CLAIMS

Claim 1 (currently amended). An adhesive sheet ~~composed~~ formed of an adhesive system comprising of a mixture of two thermoplastics T1 and T2, wherein the adhesive system has

- a) ~~the adhesive system has~~ a softening temperature of greater than 65°C and less than 125°C,
- b) a storage modulus G' at 23°C, as measured by test method A, of greater than 10^7 Pas,
- c) a loss modulus G'' at 23°C, as measured by test method A, of greater than 10^6 Pas,
- d) and a crossover, as measured by test method A, of less than 125°C.

Claim 2 (currently amended). The adhesive sheet of claim 1, ~~characterized in that wherein~~ the layer thickness is between 10 and 100 µm, ~~with particular preference between 30 and 80 µm.~~

Claim 3 (currently amended). The adhesive sheet of ~~at least one of the preceding claims, characterized in that~~ claim 1, wherein thermoplastics T1 and T2 are selected from the ~~groups~~ group consisting of copolyamides, polyethyl-vinyl acetates, polyvinyl acetates, polyolefins, polyurethanes, and copolyesters.

Claim 4 (currently amended). The adhesive sheet of ~~at least one of the preceding claims, characterized in that~~ reactive resins used additionally comprise claim 1, wherein said adhesive system further comprises reactive resins selected from the group consisting of epoxy resins, ~~and/or~~ phenolic resins ~~and/or~~ novolak resins and combinations thereof.

Claim 5 (currently amended). ~~The use of an adhesive sheet of any one of the above claims~~ A method for bonding chip modules in card bodies which comprises bonding said chip modules in said card bodies with the adhesive sheet of claim 1.

Claim 6 (currently amended). The ~~use of an adhesive sheet of any one of the above claims for bonding method of claim 5, wherein said chip modules are~~ polyimide-, polyester or epoxy-based chip modules and ~~on~~ said card bodies are PVC, ABS, PET, PC, PP or PE card bodies.

Claim 7 (currently amended). A method for producing a heat-activable adhesive tape, ~~characterized in that an~~ which comprises coating the adhesive sheet of ~~claims 1 to 4 is coated~~ claim 1 onto a release paper or a release film.

Claim ~~6~~ 8 (currently amended). The method of claim 7, ~~characterized in that~~ wherein the heat-activable adhesive tape is die-cut.

Claim ~~7~~ 9 (currently amended). ~~The method of at least one of the preceding claims, characterized in that the heat-activable adhesive tape is processed with~~ A method for implanting a chip module in a card body, which comprises implanting said chip module in said card body with a heat activable adhesive tape comprised of the adhesive sheet of claim 1 coated onto a release paper or release film, and an implanter having an implanting die at an implanting die temperature of 150°C.

Claim 10 (new). The adhesive sheet of claim 2, wherein said layer thickness is between 30 and 80 µm.